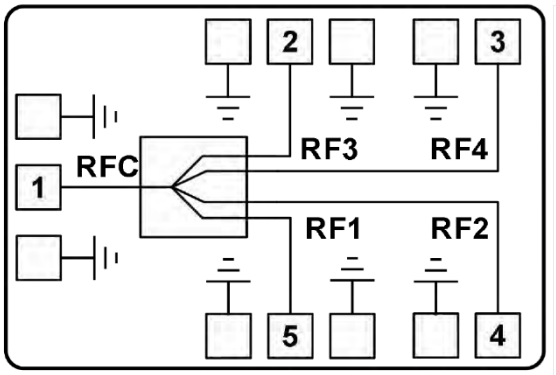
Features

- Frequency: 18-40GHz
- Insertion Loss: 0.5dB Typical
- Isolation: 22dB Typical
- Input/Output: 50Ω
- Chip Size: 2.154 x 3.215 x 0.1mm

Functional Block Diagram



Typical Applications

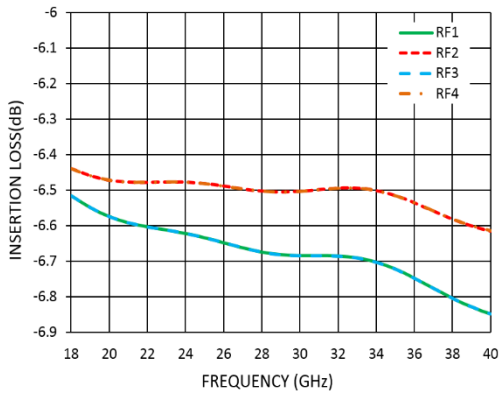
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Electrical Specifications

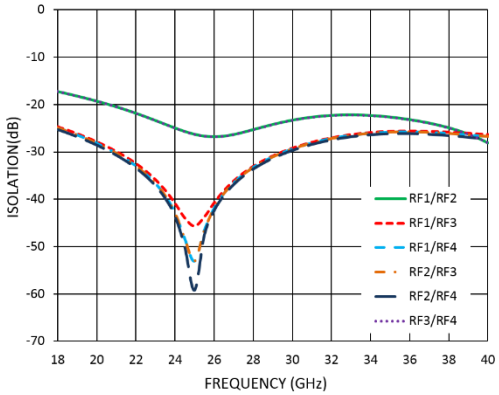
TA = +25°C ,Pin=0dBm

Parameters	Min.	Typ.	Max.	Units
Frequency	18		40	GHz
Nominal Splitter Loss		6		dB
Insertion Loss		0.5	0.9	dB
Flatness		±0.2		dB
Isolation		22		dB
Input Return Loss		18		dB
Output Return Loss		20		dB

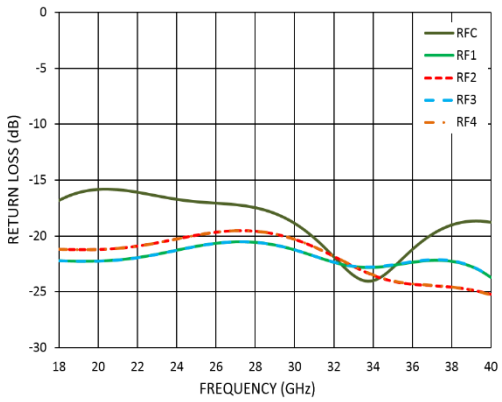
Insertion Loss vs. Frequency



Isolation vs. Frequency

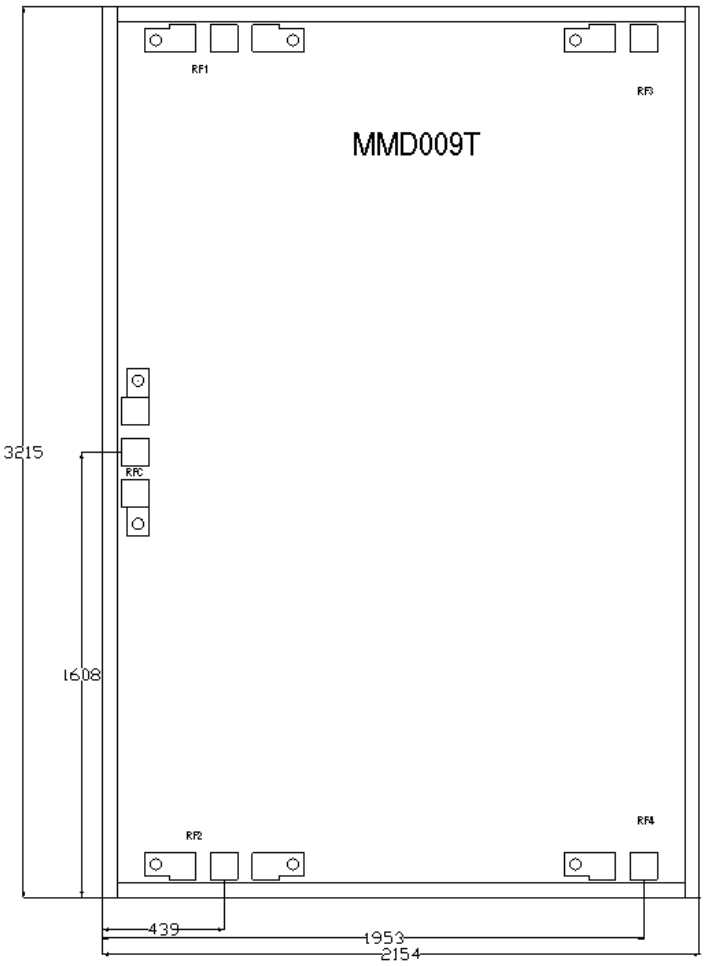


Return Loss vs. Frequency



Outline Drawing:

All Dimensions in µm



Absolute Maximum Ratings

RF Input Power	+31dBm
Operating Temperature	-55°C to +85 °C
Storage Temperature	-65°C to +150 °C

No	Symbol	Description
1	RFC	RF Common Port
2,3,4,5	RF1&RF2&RF3&RF4	RF Branch Ports

Notes:

1. **Die thickness: 100µm**
2. **RF IN/OUT bond pad is 100 x 100 µm²**
3. **Bond pad metalization: Gold**
4. **Backside metalization: Gold**
5. **Backside of the die (GND)**